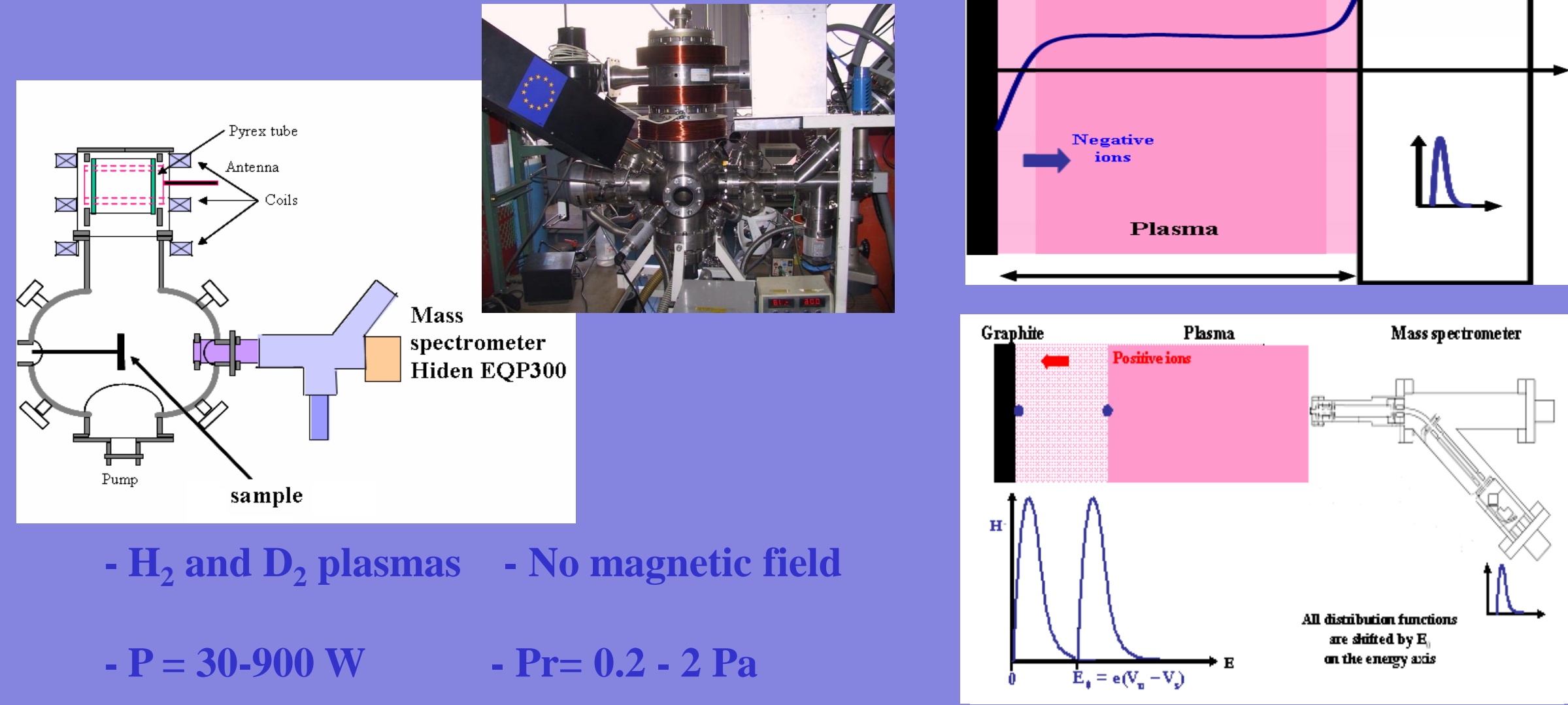


Experimental setup

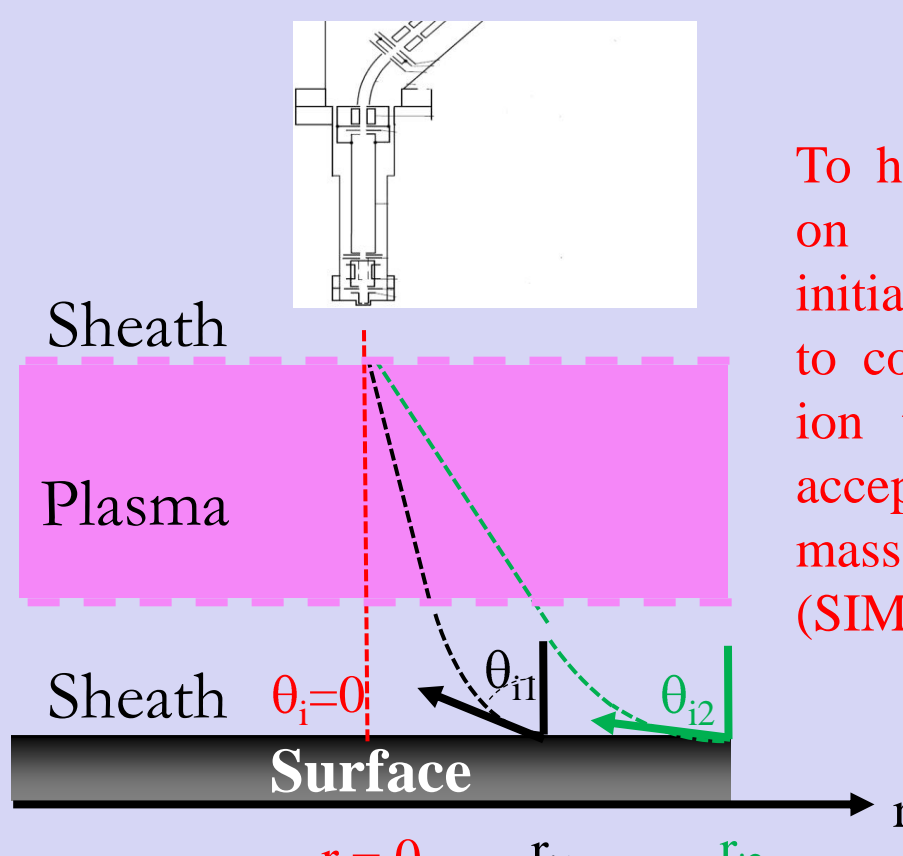


- H₂ and D₂ plasmas - No magnetic field
- P = 30-900 W - Pr = 0.2 - 2 Pa

- Upon positive ion bombardment, some negative ions are formed on the surface
- These negative ions (NI) are repelled by the sheath, cross the plasma and reach the mass spectrometer
- We record and study surface produced negative ion distribution functions (IDF)

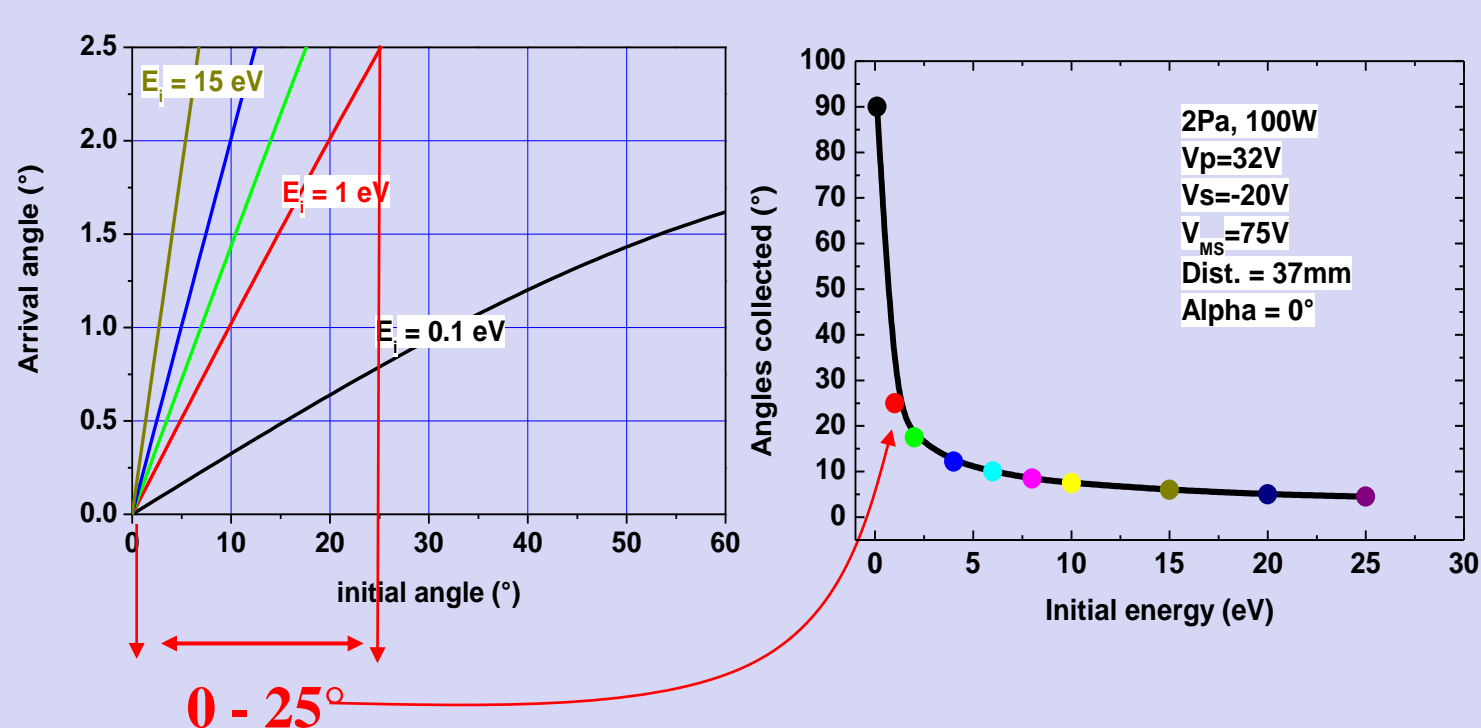
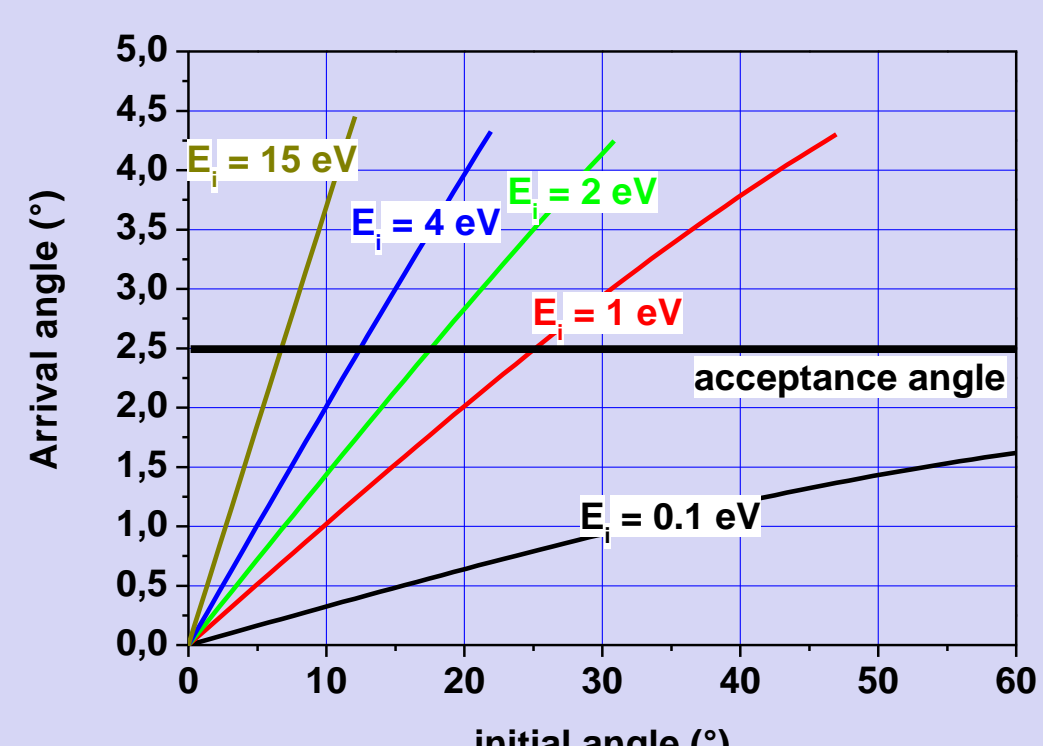
Angular controlled measurements

For each radius value (r) on the sample we detect negative ions emitted at one particular angle θ_1

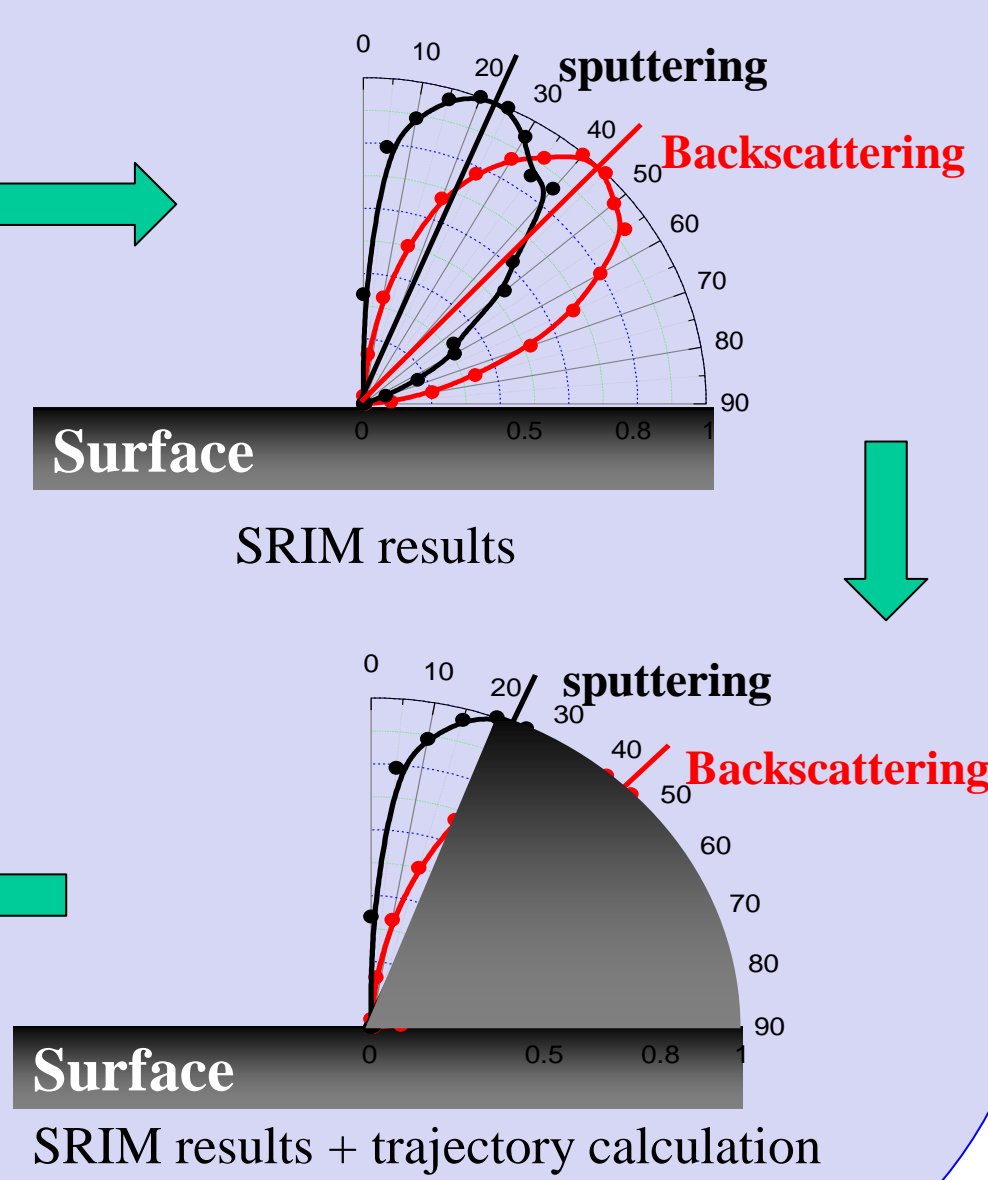


To have information on negative ion initial angle, we need to compute negative ion trajectories and acceptance angle for mass spectrometer (SIMION)

Calculations give the arrival angle (Angle on the mass spectrometer) versus the initial angle (Angle of emission on the surface) :



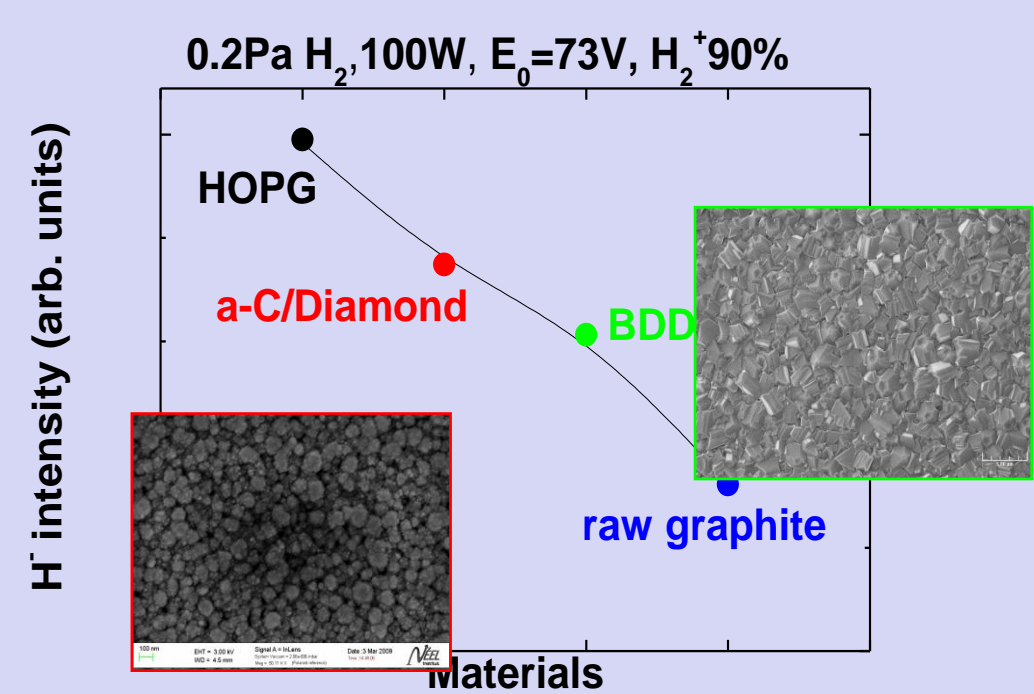
Calculations demonstrate that low energy ions are overestimated. Sputtered ions are more collected than backscattered ions.



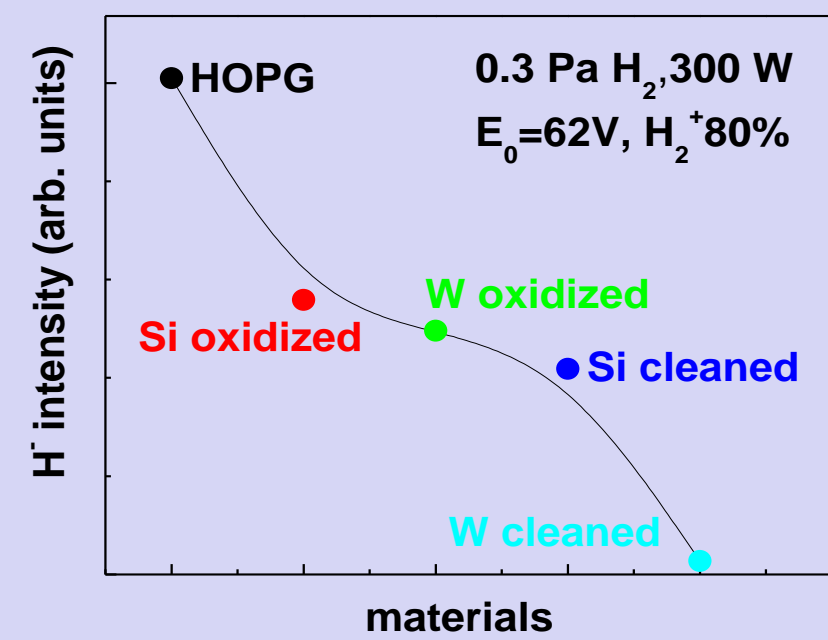
SRIM results + trajectory calculation

Calculations explain why we have different yields between SRIM and experimental result

H- production on carbon and metal or semi-conductor surfaces Intensity comparisons

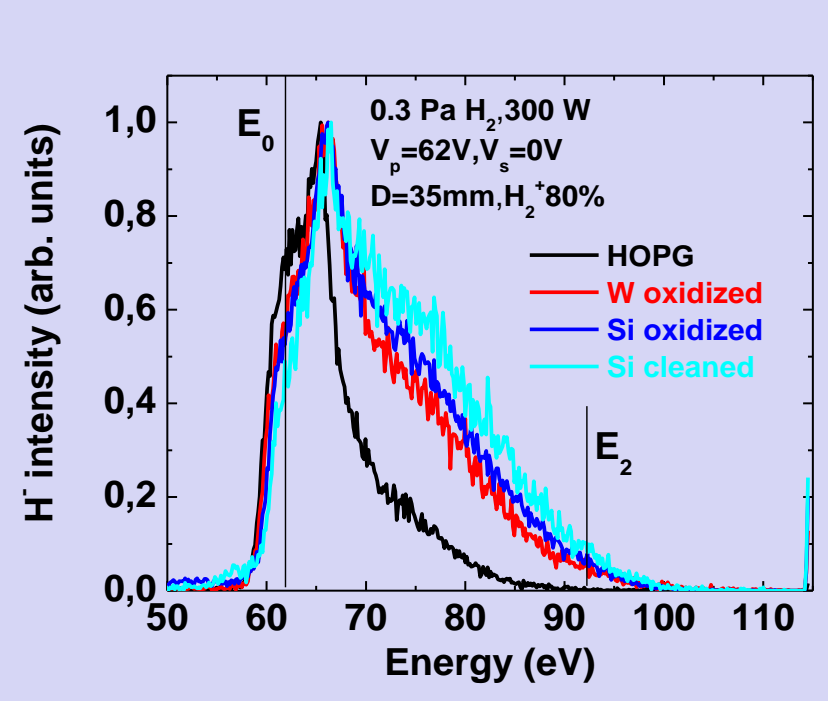
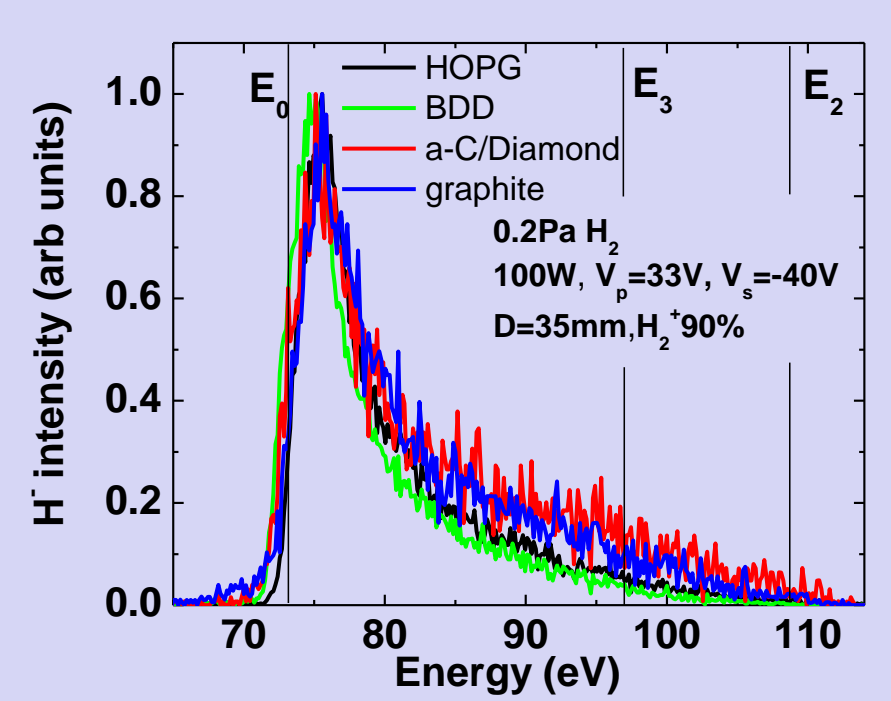


- HOPG: Highly Oriented Pyrolytic Graphite
- BDD: Boron doped diamond (LIMHP)
- a-C/Diamond: nc-Diamond or a-C (Institut Néel)
- Graphite: raw graphite from an electrode



- Oxidized materials = materials as introduced
- Cleaned materials = after 10-20 mn Ar plasma, 1Pa, 100W, 200eV positive ion bombardment
- Clean Ta, copper and clean stainless steel (not shown here) behaves similarly to clean tungsten (very low signal)

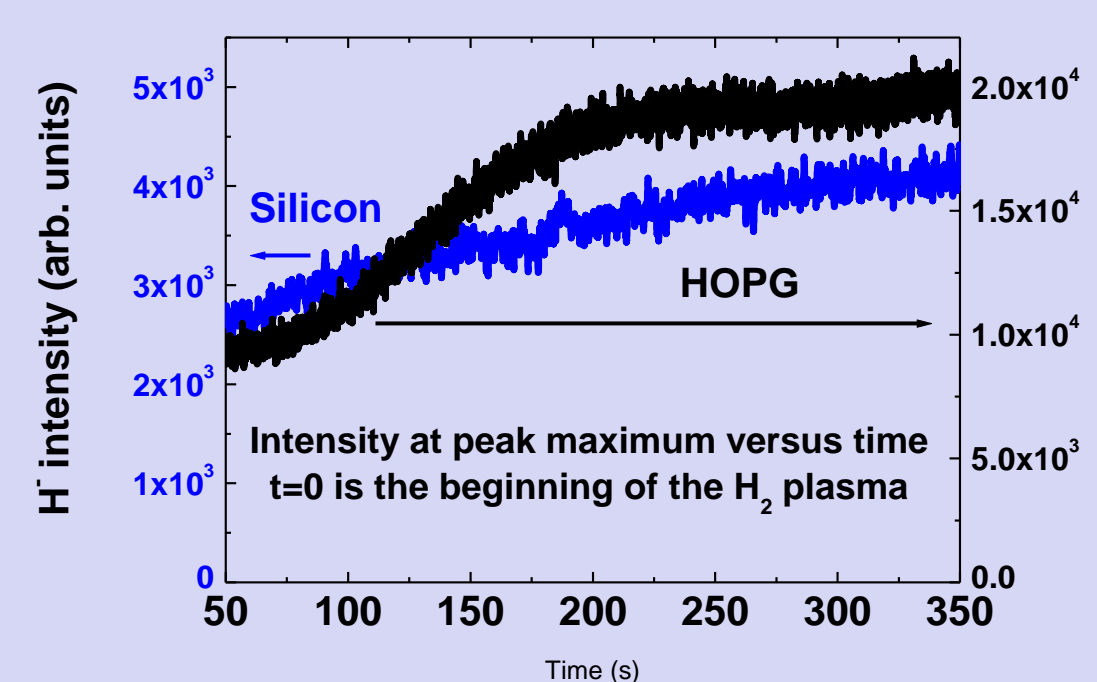
IDF shape comparisons all IDFs normalized to one



- Same shape for all carbon materials
- NI are produced by backscattering and sputtering with same proportion of each mechanism for all carbon materials

- Shapes different between HOPG and Si or W
- NI are produced by backscattering and sputtering but the proportion of each mechanism strongly differs between HOPG and metals or semi-conductors

NI intensity vs time

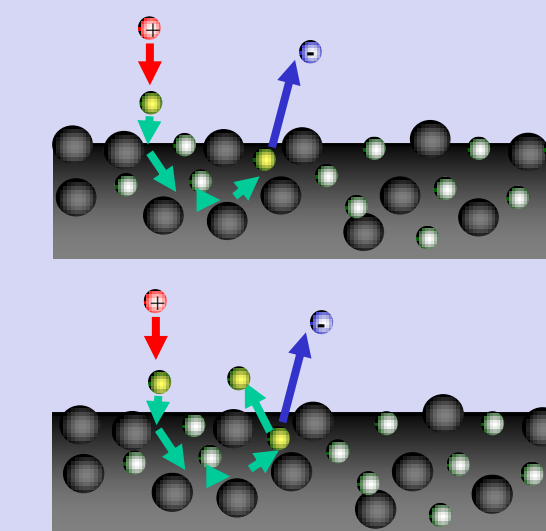


- Hydrogenation of silicon and HOPG favors NI production

H/D- production on HOPG surface

Surface production mechanisms

- I- Backscattering
- II- Sputtering

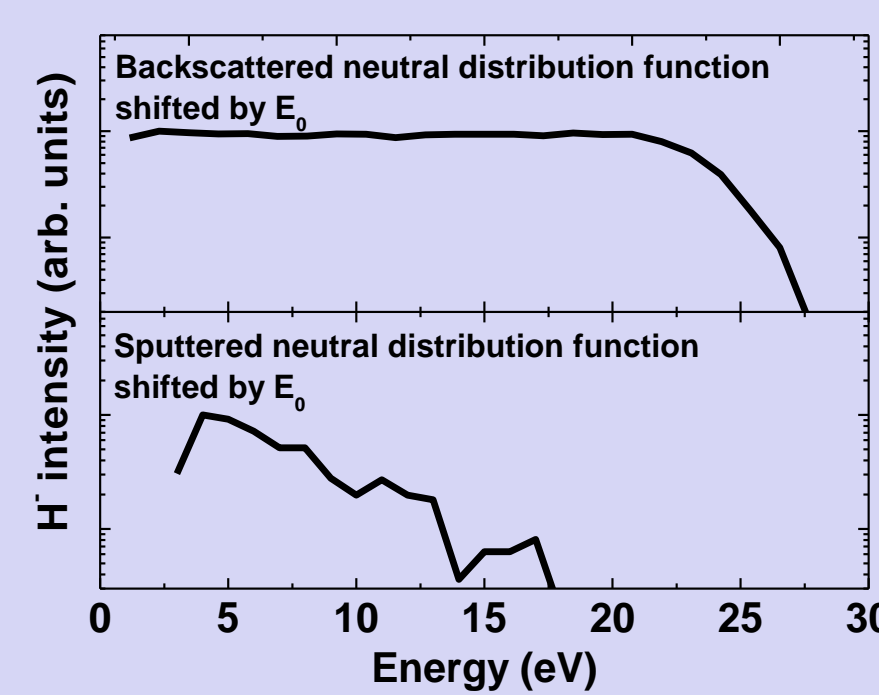


- [1] L. Schiesko, M. Carrère, G. Cartry and J.M. Layet, Plasma Sources Sci. Technol. 17, 035023 (2008)
- [2] L. Schiesko, M. Carrère, J.M. Layet, and G. Cartry, Appl. Phys. Lett. 95, 191502 (2009)
- [3] L. Schiesko, M. Carrère, J.M. Layet and G. Cartry, Plasma Sources Sci. Technol. 19 (2010) 045016

SRIM CALCULATIONS

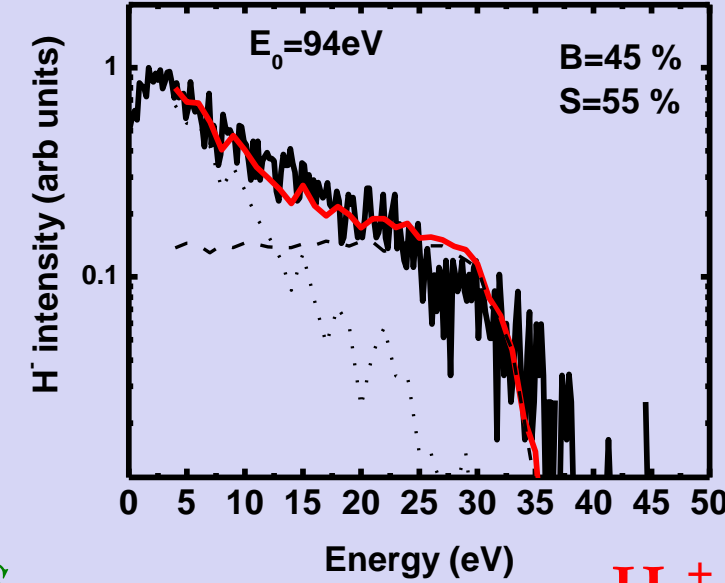
- SRIM calculates energy distribution of backscattered and sputtered neutral particles
- Positive molecular ions are assumed to be dissociated at impact and energy is assumed to be shared between fragments \Rightarrow only H+ or D+ are considered in calculations
- H_2^+ impact at energy $E_0 \equiv H^+$ impact at energy $E_0/2$
- H_3^+ impact at energy $E_0 \equiv H^+$ impact at energy $E_0/3$
- a-CH or a-CD layers (70% C – 30% H or D) are considered
- SRIM calculations are shifted by E_0 to take into account neg. ion acceleration through sheath

SRIM result

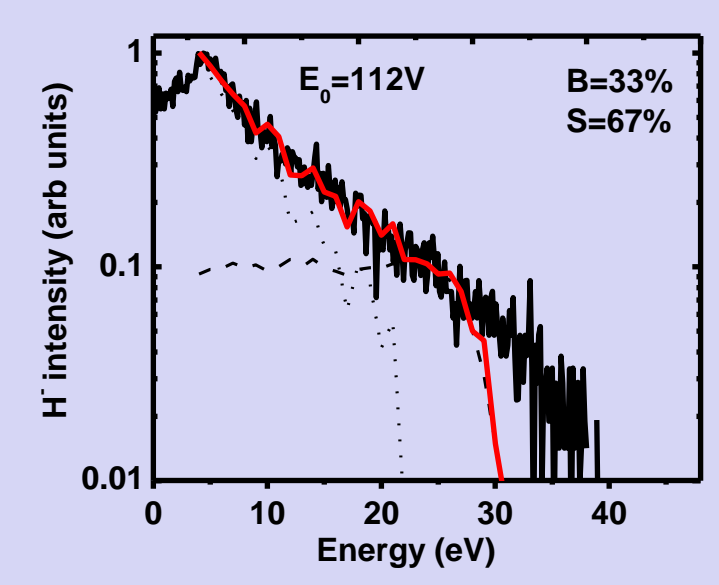


Fit experiment by: $p_1 * \text{Back} + p_2 * \text{Sputt}$

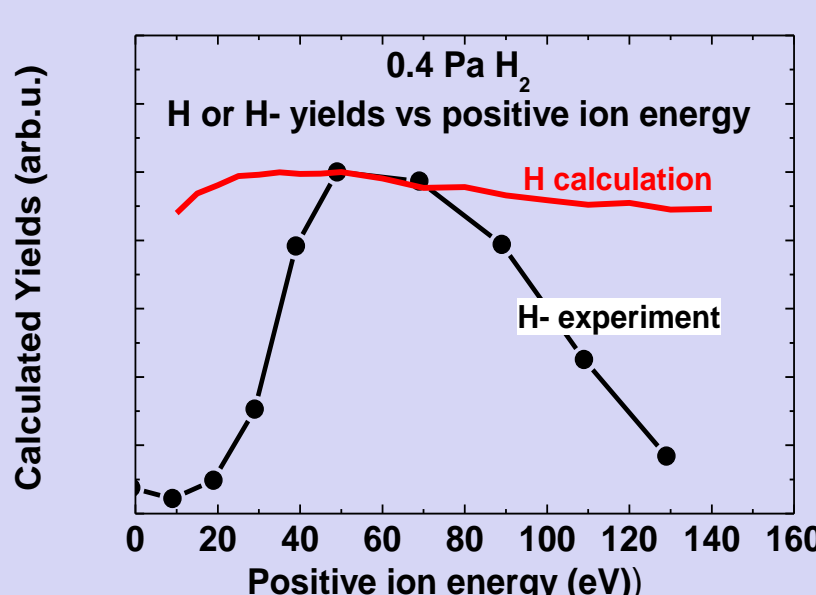
H₂⁺ dominates (90%)



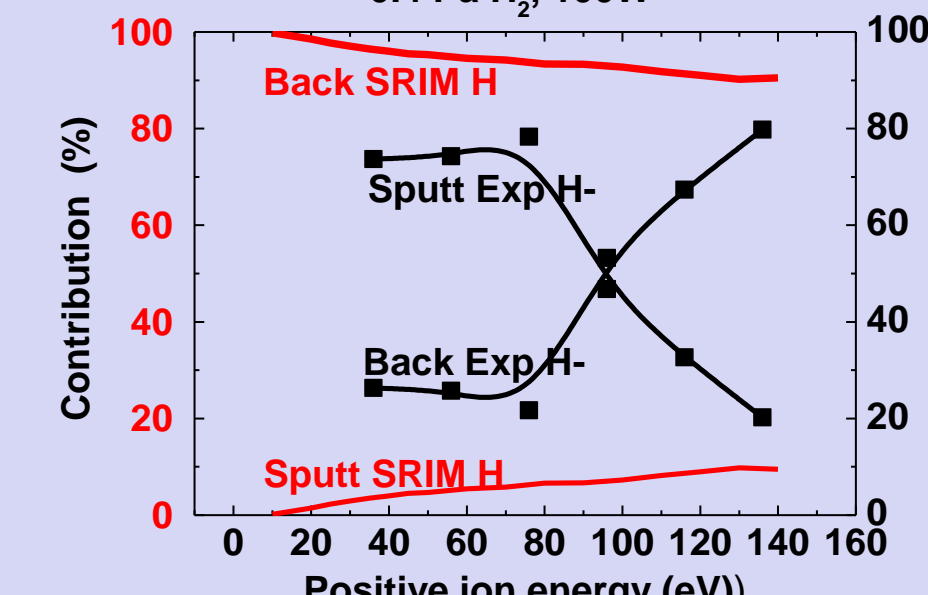
H₃⁺ dominates (87%)



- SRIM is able to reproduce experimental datas
- Confirms negative ion are formed by sputtering and backscattering mechanisms



- Experiment: strong variation with positive ion energy
- Calculations: only 10% variation
- Calculations and experiments yields are different



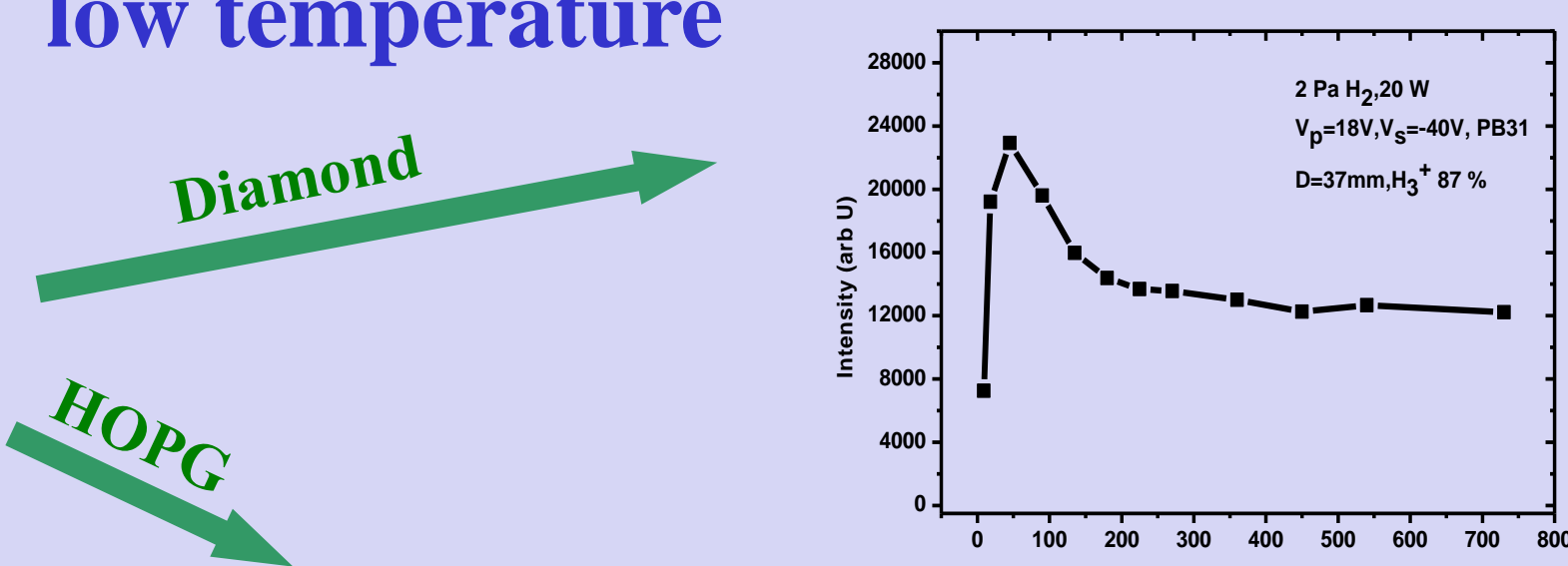
- Experiment: sputtering dominates
- Calculations: backscattering largely dominates
- Different percentage for backscattered and sputtered ions in experiment and calculation

Why? Angular controlled measurements

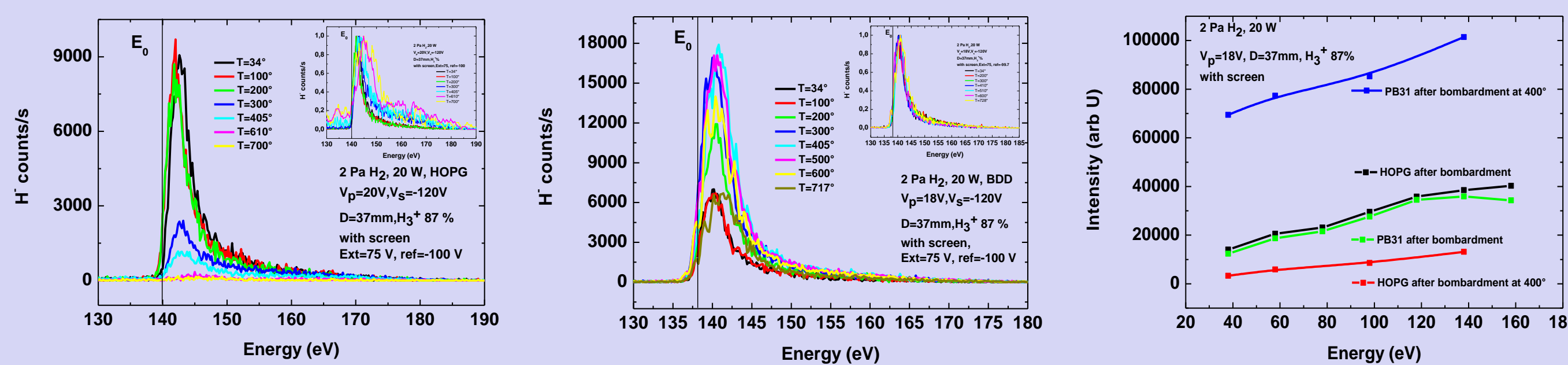
H- production on HOPG and Diamond surfaces at high and low temperature

Variation of surface state in time after the first exposure to the plasma

- Surface evolves in time due to ion bombardment
- Intensity increases to maximum and then decreases – BDD
- Intensity increases and saturates – HOPG



IDFs vs surface temperature



- Yield decreases with increasing temperature - HOPG
- Yield increases first and then decreases with increasing temperature – BDD
- HOPG and BDD behaves differently at high temperature
- Sputtering decreases with temperature for HOPG while proportions of sputtering and backscattering seem constant with temperature for BDD

Conclusions

- Angular controlled measurements are very important to understand better NI production
- HOPG is the most efficient material for producing negative ions at room temperature
- All carbon materials behave similarly at low surface temperature
- HOPG and Diamond strongly differ at high temperature
- Diamond gives 6 times more signal at 400° than HOPG at the same temperature
- Oxidized surfaces are more efficient for producing negative ions than clean surfaces
- Clean metal surfaces are not efficient at all to produce negative ions